

The interior view of the Windows NT^{\otimes} powered CAMALOT XyflexPro.

M O D U L A R I T Y = F L E X I B I L I T Y

30,000 DPH





100,000 - 120,000 DPH



LINE OPTIMIZATION AND PROGRAMMING ACHIEVED THROUGH ONE HOST COMPUTER.



A COOKSON ELECTRONICS COMPANY

XYFLEXPRO[™] SPECIFICATIONS

	SMALL PLATFORM	LARGE PLATFORM
Footprint (W x D x H)	31"* x 50" x 55" (787mm x 1268mm x 1397mm)	39"* x 62" x 55" (991mm x 1575mm x 1397mm)
Max. board size (X - Y)	13" x 10" (330mm x 254mm)	22" x 20" (559mm x 508mm)
Minimum conveyor width	1" (25mm)	ı" (25mm)
Above board clearance	1" (25mm)	1" (25mm)
Under board clearance	1.2" (30.5mm)	1.2" (30.5mm)
Dot placement accuracy	0.003" @ 3 sigma (±75mm)	0.003" @ 3 sigma (±75mm)
Dispensing rate per platform	30,000 dph (application dependent)	30,000 dph (application dependent)
DISPENSING	RATE INCREASES WITH MULTIPLE PLATFORM LINK-UP	
Computer operating system	Windows NT®	
Program storage	6.5 GB Hard Drive; 1.44 MB 3.5" floppy disk, zip drive and CD-ROM, Pentium II, 450 MHz	
Transport height	35.8" to 38.25" (909mm - 971mm) SMEMA with riser pad	
Power requirements	208-220V AC, 20 Amp max., 50/60 Hz, Single Phase, 3 wire grounded	
Pneumatic requirements	10 SCFM (30m³/min) of clean dry air, 5 micron filtered air at > 80 PSI (5.5 bars)	

RECOMMENDED MACHINE CONFIGURATION BY APPLICATION

	S M T	SEMICONDUCTOR
Material	Solder paste, adhesive, conductive adhesive	Underfill, encapsulation, lid seal,
		thermal grease
Pump style	Dot Dispense Unit (D.U.) with auger screw	Multi-piston pump
		Heated line D.U. with auger screw
Needle	Footed	Non-footed
		Heated (40C ±3C)
Weight calibration	N/A	Available
Substrate Heat (≤100C ±3C)	None	Pre and post
Height sensing	LDVT/Touch Probe	LDVT/Touch Probe
Needle calibration	Standard	Standard
Pre-dispense	Standard	Standard
*Conveyor width		

www.speedlinetechnologies.com

Speedline Technologies, Inc. WORLD HEADQUARTERS 16 Forge Park Franklin, MA 02038 Tel: (508) 520-0083 Fax: (508) 520-2288

Speedline Technologies, Inc. ACCEL Division 1825 East Plano Parkway Suite 250 Plano, TX 75074-8129 Tel: (972) 424-3525 Fax: (972) 424-7526 Speedline Technologies, Inc. CAMALOT Division 145 Ward Hill Avenue Haverhill, MA 01835 Tel: (978) 373-3742 Fax: (978) 521-2105

Speedline Technologies, Inc. ELECTROVERT Division Highway 5 South Camdenton, MO 65020 Tel: (573) 346-3341 Fax: (573) 346-5554

Speedline Technologies, Inc. MPM Division 16 Forge Park Franklin, MA 02038 Tel: (508) 520-0083 Fax: (508) 520-2288

Speedline Technologies, Inc. CUSTOMER SUPPORT CENTER 580-A Tollgate Road Elgin, IL 60123 Tel: (847) 695-5750 Fax: (847) 695-5815 Speedline Technologies, Inc. SPECIALTY COATING SYSTEMS 5707 West Minnesota Street Indianapolis, IN 46241 Tel: (317) 244-1200 Fax: (317) 240-2073

Speedline Technologies, Ltd.

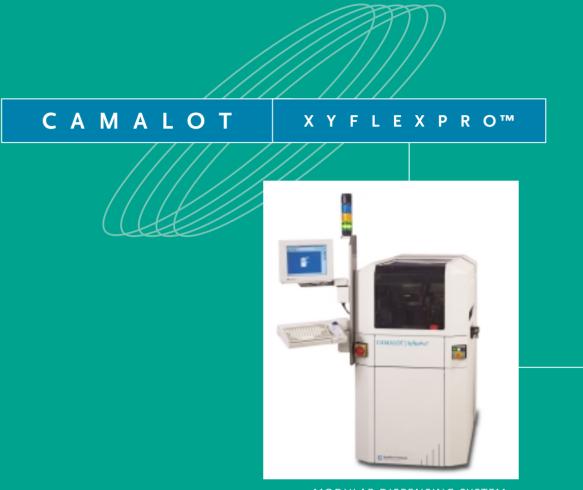
Pincents Kiln Industrial Park Reading, Berkshire RG31 7SD United Kingdom Tel: +44 (0) 118-930-1400 Fax: +44 (0) 118-930-1401

Speedline Technologies GmbH Daimlerstrasse 1E 63303 Dreieich Germany Tel: +49 (0) 6103-832-0 Fax: +49 (0) 6103-832-299

Speedline Technologies Asia 150 Kampong Ampat KA Centre #05-08 Singapore 368324 Tel: (65) 286-6635 Fax: (65) 289-9411

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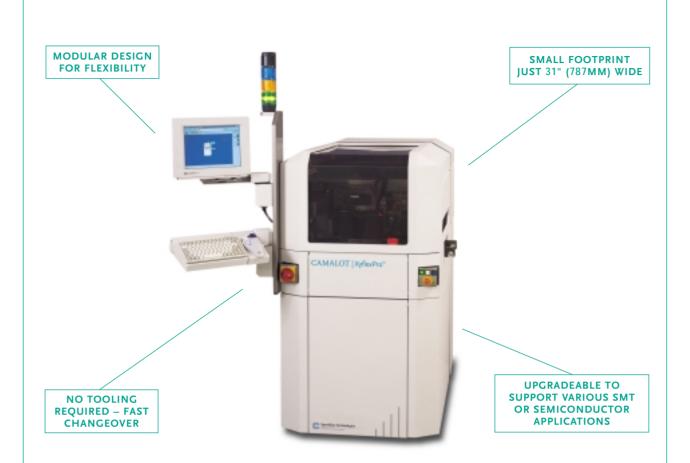
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MODULAR DISPENSING SYSTEM

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CAMALOT XYFL EXPRO™



CAMALOT XyflexPro[™] Modular Dispensing System

The CAMALOT XyflexPro[™] Modular Dispensing System brings together many of the advanced dispensing technologies in the converging SMT and semiconductor packaging markets to meet the need for medium- to high-speed dispensing. Using a traditional x-y gantry, XyflexPro provides a large dispense area with minimal footprint of just 31" (787mm) wide. Its modular design allows two, three or four machines to be installed in-line, all controlled from a single PC-based controller and Windows NT[®] user interface. This makes it easy to optimize line balancing across multiple dispense patterns to achieve high throughput. XyflexPro is capable of dispense speeds of 30,000 to 120,000 dots per hour (application dependent).

System Benefits

FEATURES

- > Compact footprint-Only 31" (787mm) wide (conveyor width).
- > Modular and flexible-Multiple machine link-up allows variable throughput.
- > **Programmable** through one computer and user interface.
- > **Two versions available**–for SMT and semiconductor applications.
- > Two platform sizes for flexible board handling.

UNIQUE DESIGN

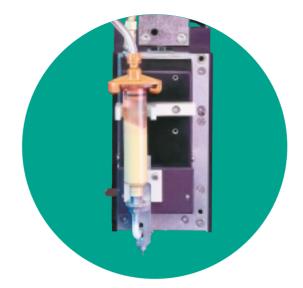
XyflexPro is available in two versions. The "large" version offers a 22" x 20" dispense area, and the "small" version has a 13" x 10" dispense area. This is a radically new design approach that features a single, modular platform that can accommodate a variety of easy-to-add accessories.

BROAD RANGE OF CAPABILITIES

XyflexPro allows users to custom-configure manufacturing processes for either SMT or semiconductor packaging applications. The system can dispense dots of surface mount adhesive, conductive adhesive or solder paste for SMT applications. It can also dispense lines of encapsulant or underfill for semiconductor packaging applications.

FLEXIBLE

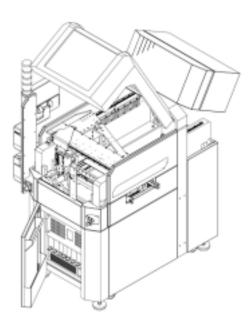
Because of the modular XyflexPro design, users find it easy to add options and accessories. Minimal engineering time and effort are required for upgrades. Product changeover is easy, requiring minimal tooling.



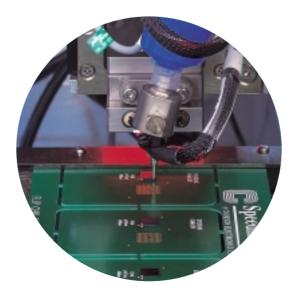
Miniaturized Z-head houses camera and Z-sensor. Shown with Snap-In Dispense Head for quick and easy changeover, maximizing throughput and uptime.



Optional Multi-Piston Pump and Automatic Weight Calibration System.



THREE-QUARTER VIEW

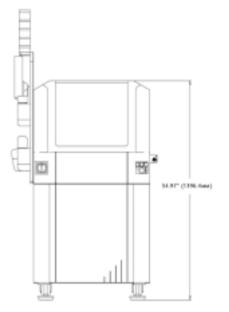


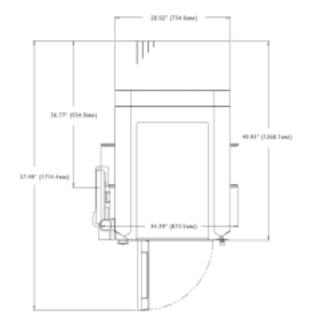
Choose optional accessories to configure SMT or Semiconductor applications.

XyflexPro[™] Dimensions

FRONT VIEW

TOP VIEW





SIDE VIEW



